

Nordson YESTECH's advanced 3D imaging technology offers high-speed PCB inspection with exceptional defect coverage. With one top down viewing camera, four side viewing cameras and 2D + 3D inspection, the FX-940 ULTRA inspects solder joints and verifies correct part assembly enabling users to improve quality and increase throughput.

Programming the FX-940 ULTRA is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program including solder and lead inspections. The FX-940 ULTRA utilizes a standard package library to simplify training and ensure program portability across manufacturing lines.

Advanced LED lighting and newly available image processing technology integrates several techniques, including 3D inspection, color inspection, normalized correlation and rule-based algorithms, to provide complete inspection coverage with an unmatched low false failure rate.

Configurable for all line positions, the FX-940 ULTRA is equally effective for paste, pre / post-reflow and final assembly inspection. Off-line programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

Features:

- 5 axis 3D NYTVISION Technology
- Advanced 2D + 3D inspection
- Multi-fringe digital projection
- 1 top-down and 4 side viewing cameras
- Automatic programming tools: < 30 minutes
- High defect coverage / low false failure
- SPC data collection & reporting

Automated 3D Inspection for:

- Co-planarity of chips, BGAs and other height sensitive devices
- Solder defects / paste
- Lead defects / lifted leads
- Component presence and position
- Correct part / polarity
- Through-hole parts



FX-940 ULTRA 3D AOI In-line PCB inspection

Specifications

Model

FX-940 ULTRA 3D

Specifications

Throughput:

Maximum Inspection Area:

Clearance:

Minimum Component Size:

False Calls:

Defects Detected:

Software

Algorithms:

Data Requirements:

CAD Translation Package:

Off-line Software:

SPC Software:

Data Outputs:

Hardware

Material Handling:

Lighting:

Conveyor:

Facilities

Power: Air input:

mpat.

Footprint:

Weight:

Multi-function system with top-down viewing,

4 side viewing cameras

2D + 3D Inspections

Up to 25 sq. in./sec. > 1.5 million components per hour

16" x 19" (406mm x 480mm)

2" (50mm) top and bottom

01005 with high magnification option

<500 PPM (<0.05% typical)

Part: position, missing, wrong, polarity,

skew, tombstone

Lead: bent, lifted, bridging

Solder: open, insufficient, short, solder balls

Height measurements, color, OCV, OCR, barcode recognition, both image and rule-based algorithms.

ASCII Text, X-Y position, part #, ref. #, polarity
Aegis, Unicam, Fabmaster, YESTECH CAD Utility
Optional - Rework, Review and Program Creation
Optional - Real time local and remote monitoring of factors.

Optional - Real-time local and remote monitoring of first pass yield, defect trends and machine utilization.

Text, SQL, ODBC, MS Access

SMEMA, dual direction auto width conveyor,

pass / fail signals, board clamping

Multiangle LED

Dual lane conveyor, heavy duty chain conveyor, 3 stage

and large board option

110-220VAC, 50/60 Hz, 15 amps 60 PSI min., 1/4" air hose, 2 CFM

39" x 52" x 60" (1000mm x 1329mm x 1531mm)

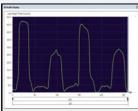
950 lbs (430 kg)



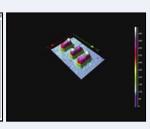
3D image of lifted lead.



Color map of lifted lead.



Lead height profile.



Lifted components.

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